

# VS-32CTQ...SPbF, VS-32CTQ...-1PbF Series

# Vishay Semiconductors

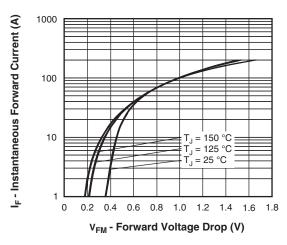
ELECTRICAL SPECIFICATIONS	ECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS	
		15 A	T <sub>.I</sub> = 25 °C	0.49	V	
Maximum forward voltage drop	V <sub>FM</sub> <sup>(1)</sup>	30 A	11 = 23 0	0.58		
See fig. 1		15 A	T 105 °C	0.40		
		30 A	T <sub>J</sub> = 125 °C	0.53		
Maximum reverse leakage current	I <sub>RM</sub> <sup>(1)</sup>	T <sub>J</sub> = 25 °C	V - Poted V	1.75	mA	
See fig. 2	IRM (1)	T <sub>J</sub> = 125 °C	V <sub>R</sub> = Rated V <sub>R</sub>	97	IIIA	
Threshold voltage	V <sub>F(TO)</sub>	$I_{J} = I_{J}$ maximum		V		
Forward slope resistance	r <sub>t</sub>			9.09	mΩ	
Maximum junction capacitance per leg	C <sub>T</sub>	V <sub>R</sub> = 5 V <sub>DC</sub> (test signal range	ge 100 kHz to 1 MHz), 25 °C	1300	pF	
Typical series inductance per leg	L <sub>S</sub>	Measured lead to lead 5 m	nm from package body	8.0	nΗ	
Maximum voltage rate of change	dV/dt	Rated V <sub>R</sub>		10 000	V/µs	

#### Note

 $<sup>^{(1)}\,</sup>$  Pulse width < 300  $\mu s,$  duty cycle < 2 %

THERMAL - MECHANI	THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum junction and storage temperature range		T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C	
Maximum thermal resistance, junction to case per leg		R <sub>thJC</sub>	DC operation See fig. 4	3.25	°C/W	
Typical thermal resistance, case to heatsink		R <sub>thCS</sub>	Mounting surface, smooth and greased	0.50	C/VV	
Approximate weight				2	g	
Approximate weight				0.07	oz.	
Manustina taun	minimum			6 (5)	kgf · cm	
Mounting torque	maximum			12 (10)	(lbf $\cdot$ in)	
			Consider D2DAV	32CT0	Q025S	
Mandring device	ultipa dovino		Case style D <sup>2</sup> PAK		32CTQ030S	
Marking device				32CTC	025-1	
			Case style TO-262		32CTQ030-1	

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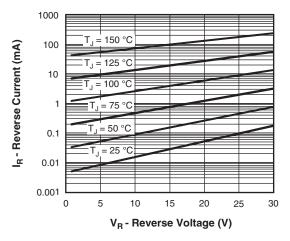


Fig. 1 - Maximum Forward Voltage Drop Characteristics

Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

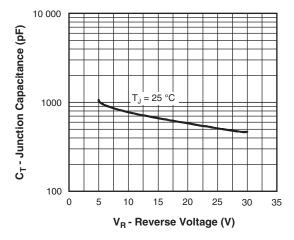


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

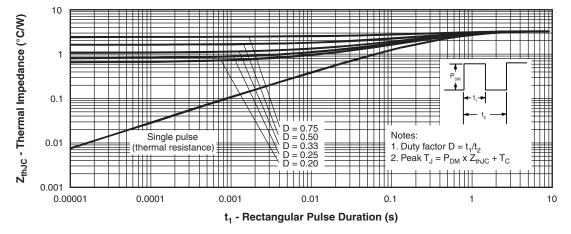


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

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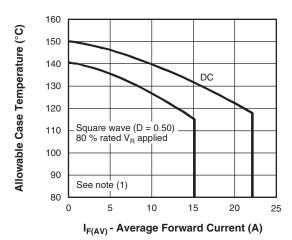


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

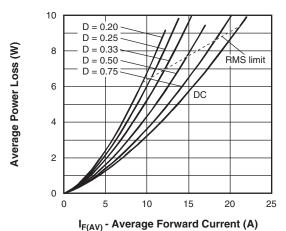


Fig. 6 - Forward Power Loss Characteristics

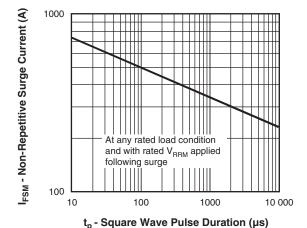


Fig. 7 - Maximum Non-Repetitive Surge Current

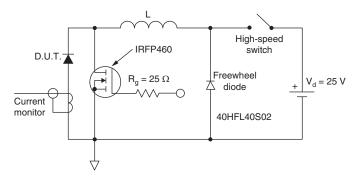


Fig. 8 - Unclamped Inductive Test Circuit

#### Note

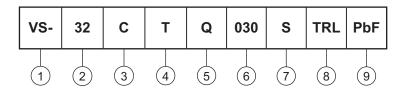
 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6);} \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = 80 \text{ \% rated } V_R \\ \end{array}$ 

## VS-32CTQ...SPbF, VS-32CTQ...-1PbF Series

Vishay Semiconductors

#### **ORDERING INFORMATION TABLE**

**Device code** 



1 - Vishay Semiconductors product

2 - Current rating (30 A)

3 - Circuit configuration: C = common cathode

4 - T = TO-220

5 - Schottky "Q" series

6 - Voltage ratings 025 = 25 V 030 = 30 V

7 - • S = D<sup>2</sup>PAK

• -1 = TO-262

8 - • None = tube (50 pieces)

• TRL = tape and reel (left oriented - for D<sup>2</sup>PAK only)

• TRR = tape and reel (right oriented - for D<sup>2</sup>PAK only)

9 - PbF = lead (Pb)-free

ORDERING INFORMATI	ORDERING INFORMATION (Example)					
PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-32CTQ025SPBF	50	1000	Antistatic plastic tubes			
VS-32CTQ025STRRPBF	800	800	13" diameter plastic tape and reel			
VS-32CTQ025STRLPBF	800	800	13" diameter plastic tape and reel			
VS-32CTQ025-1PBF	50	1000	Antistatic plastic tubes			
VS-32CTQ030SPBF	50	1000	Antistatic plastic tubes			
VS-32CTQ030STRRPBF	800	800	13" diameter plastic tape and reel			
VS-32CTQ030STRLPBF	800	800	13" diameter plastic tape and reel			
VS-32CTQ030-1PBF	50	1000	Antistatic plastic tubes			

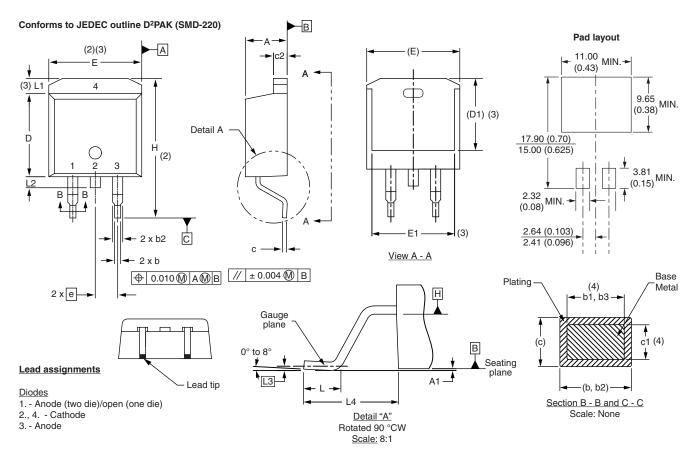
LINKS TO RELATED DOCUMENTS				
Dimensions	TO-263AB (D <sup>2</sup> PAK)	<sup>2</sup> PAK) <u>www.vishay.com/doc?95046</u>		
Dimensions	TO-262AA	www.vishay.com/doc?95419		
Part marking information		www.vishay.com/doc?95008		
Packaging information		www.vishay.com/doc?95032		



## Vishay Semiconductors

# **D<sup>2</sup>PAK, TO-262**

#### **DIMENSIONS - D<sup>2</sup>PAK** in millimeters and inches



	1		1		t .
SYMBOL	MILLIMETERS		INC	NOTES	
STIMBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100 BSC		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25	BSC	0.010	BSC	
L4	4.78	5.28	0.188	0.208	

#### Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- $^{(3)}\,$  Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch

(7) Outline conforms to JEDEC outline TO-263AB

Document Number: 95014 Revision: 31-Mar-09

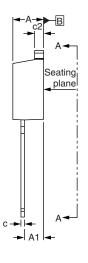
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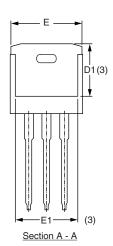
D<sup>2</sup>PAK, TO-262



#### **DIMENSIONS - TO-262** in millimeters and inches

# 





**⊕** 0.010 **M** A **M** B

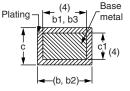
#### Lead assignments



#### **Diodes**

1. - Anode (two die)/open (one die) 2., 4. - Cathode

3. - Anode



Section B - B and C - C Scale: None

SYMBOL	MILLIM	IETERS	INC	NOTES	
	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100	D BSC	
L	13.46	14.10	0.530	0.555	
L1	=	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches

(6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline

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